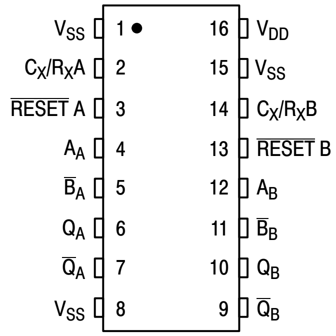
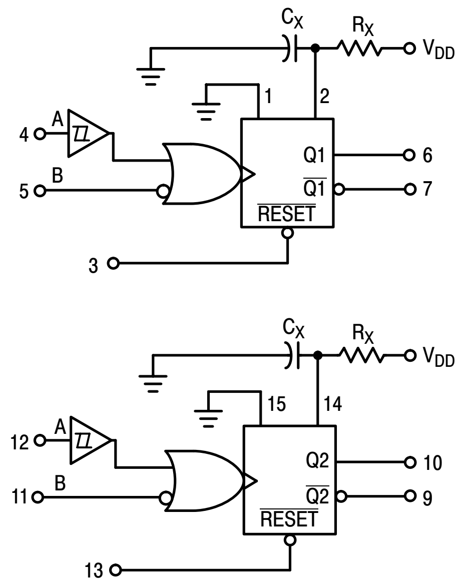
PIN ASSIGNMENT

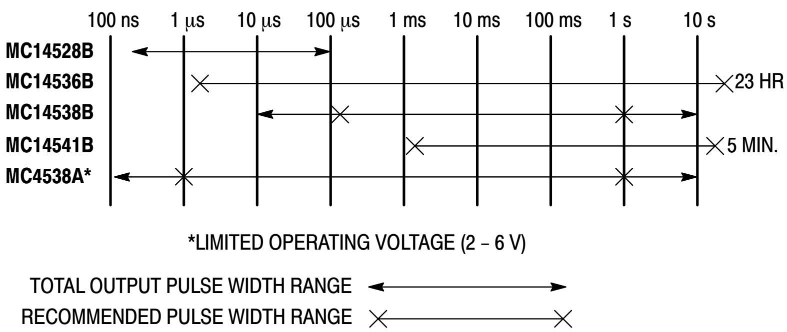


BLOCK DIAGRAM



R_X AND C_X ARE EXTERNAL COMPONENTS.
V_{DD} = PIN 16
V_{SS} = PIN 8, PIN 1, PIN 15

ONE−SHOT SELECTION GUIDE



ORDERING INFORMATION

Device	Package	Shipping†
MC14538BCP	PDIP−16	500 Units / Rail
MC14538BCPG	PDIP−16 (Pb−Free)	500 Units / Rail
MC14538BD	SOIC−16	48 Units / Rail
MC14538BDG	SOIC−16 (Pb−Free)	48 Units / Rail
MC14538BDR2	SOIC−16	2500 Units / Tape & Reel
MC14538BDR2G	SOIC−16 (Pb−Free)	2500 Units / Tape & Reel
MC14538BDW	SOIC−16 WB	47 Units / Rail
MC14538BDWR2	SOIC−16 WB	1000 Units / Tape & Reel
MC14538BDWR2G	SOIC−16 WB (Pb−Free)	1000 Units / Tape & Reel
MC14538BDTR2	TSSOP−16*	2500 Units / Tape & Reel
MC14538BF	SOEIAJ−16	50 Units / Rail
MC14538BFG	SOEIAJ−16 (Pb−Free)	50 Units / Rail
MC14538BFEL	SOEIAJ−16	2000 Units / Tape & Reel
MC14538BFELG	SOEIAJ−16 (Pb−Free)	2000 Units / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
*This package is inherently Pb−Free.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	− 55°C		25°C			125°C		Unit
			Min	Max	Min	Typ (Note 2)	Max	Min	Max	
Output Voltage "0" Level V_{in} = V_{DD} or 0	V_{OL}	5.0 10 15	− − −	0.05 0.05 0.05	− − −	0 0 0	0.05 0.05 0.05	− − −	0.05 0.05 0.05	Vdc
"1" Level V_{in} = 0 or V_{DD}	V_{OH}	5.0 10 15	4.95 9.95 14.95	− − −	4.95 9.95 14.95	5.0 10 15	− − −	4.95 9.95 14.95	− − −	Vdc
Input Voltage "0" Level (V_O = 4.5 or 0.5 Vdc) (V_O = 9.0 or 1.0 Vdc) (V_O = 13.5 or 1.5 Vdc)	V_{IL}	5.0 10 15	− − −	1.5 3.0 4.0	− − −	2.25 4.50 6.75	1.5 3.0 4.0	− − −	1.5 3.0 4.0	Vdc
"1" Level (V_O = 0.5 or 4.5 Vdc) (V_O = 1.0 or 9.0 Vdc) (V_O = 1.5 or 13.5 Vdc)	V_{IH}	5.0 10 15	3.5 7.0 11	− − −	3.5 7.0 11	2.75 5.50 8.25	− − −	3.5 7.0 11	− − −	Vdc
Output Drive Current (V_{OH} = 2.5 Vdc) Source (V_{OH} = 4.6 Vdc) (V_{OH} = 9.5 Vdc) (V_{OH} = 13.5 Vdc)	I_{OH}	5.0 5.0 10 15	– 3.0 – 0.64 – 1.6 – 4.2	− − − −	– 2.4 – 0.51 – 1.3 – 3.4	– 4.2 – 0.88 – 2.25 – 8.8	− − − −	– 1.7 – 0.36 – 0.9 – 2.4	− − − −	mAdc
(V_{OL} = 0.4 Vdc) Sink (V_{OL} = 0.5 Vdc) (V_{OL} = 1.5 Vdc)	I_{OL}	5.0 10 15	0.64 1.6 4.2	− − −	0.51 1.3 3.4	0.88 2.25 8.8	− − −	0.36 0.9 2.4	− − −	mAdc
Input Current, Pin 2 or 14	I_{in}	15	−	±0.05	−	±0.00001	±0.05	−	±0.5	µAdc
Input Current, Other Inputs	I_{in}	15	−	±0.1	−	±0.00001	±0.1	−	±1.0	µAdc
Input Capacitance, Pin 2 or 14	C_{in}	−	−	−	−	25	−	−	−	pF
Input Capacitance, Other Inputs (V_{in} = 0)	C_{in}	−	−	−	−	5.0	7.5	−	−	pF
Quiescent Current (Per Package) Q = Low, $\overline{Q}$ = High	I_{DD}	5.0 10 15	− − −	5.0 10 20	− − −	0.005 0.010 0.015	5.0 10 20	− − −	150 300 600	µAdc
Quiescent Current, Active State (Both) (Per Package) Q = High, $\overline{Q}$ = Low	I_{DD}	5.0 10 15	− − −	2.0 2.0 2.0	− − −	0.04 0.08 0.13	0.20 0.45 0.70	− − −	2.0 2.0 2.0	mAdc
Total Supply Current at an external load capacitance (C_L) and at external timing network (R_X, C_X) (Note 3)	I_T	5.0 10	$I_T = (3.5 \times 10^{-2})\ R_XC_Xf + 4C_Xf + 1 \times 10^{-5}\ C_Lf$ $I_T = (8.0 \times 10^{-2})\ R_XC_Xf + 9C_Xf + 2 \times 10^{-5}\ C_Lf$ $I_T = (1.25 \times 10^{-1})\ R_XC_Xf + 12C_Xf + 3 \times 10^{-5}\ C_Lf$ where: I_T in µA (one monostable switching only), C_X in µF, C_L in pF, R_X in k ohms, and f in Hz is the input frequency.							µAdc

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
3. The formulas given are for the typical characteristics only at 25°C.

SWITCHING CHARACTERISTICS (Note 4) (C_L = 50 pF, T_A = 25°C)

Characteristic	Symbol	V_{DD} Vdc	All Types Min	Typ (Note 5)	Max	Unit
Output Rise Time	t_{TLH}					ns
t_{TLH} = (1.35 ns/pF) C_L + 33 ns		5.0	–	100	200	
t_{TLH} = (0.60 ns/pF) C_L + 20 ns		10	–	50	100	
t_{TLH} = (0.40 ns/pF) C_L + 20 ns		15	–	40	80	
Output Fall Time	t_{THL}					ns
t_{THL} = (1.35 ns/pF) C_L + 33 ns		5.0	–	100	200	
t_{THL} = (0.60 ns/pF) C_L + 20 ns		10	–	50	100	
t_{THL} = (0.40 ns/pF) C_L + 20 ns		15	–	40	80	
Propagation Delay Time	t_{PLH},					ns
A or B to Q or $\overline{Q}$	t_{PHL}					
t_{PLH}, t_{PHL} = (0.90 ns/pF) C_L + 255 ns		5.0	–	300	600	
t_{PLH}, t_{PHL} = (0.36 ns/pF) C_L + 132 ns		10	–	150	300	
t_{PLH}, t_{PHL} = (0.26 ns/pF) C_L + 87 ns		15	–	100	220	
$\overline{Reset}$ to Q or $\overline{Q}$						ns
t_{PLH}, t_{PHL} = (0.90 ns/pF) C_L + 205 ns		5.0	–	250	500	
t_{PLH}, t_{PHL} = (0.36 ns/pF) C_L + 107 ns		10	–	125	250	
t_{PLH}, t_{PHL} = (0.26 ns/pF) C_L + 82 ns		15	–	95	190	
Input Rise and Fall Times	t_r, t_f	5	–	–	15	µs
$\overline{Reset}$		10	–	–	5	
		15	–	–	4	
B Input		5	–	300	1.0	ms
		10	–	1.2	0.1	
		15	–	0.4	0.05	
A Input		5				–
		10		No Limit		
		15				
Input Pulse Width	t_{WH},	5.0	170	85	–	ns
A, B, or Reset	t_{WL}	10	90	45	–	
		15	80	40	–	
Retrigger Time	t_{rr}	5.0	0	–	–	ns
		10	0	–	–	
		15	0	–	–	
Output Pulse Width — Q or $\overline{Q}$	T					µs
Refer to Figures 8 and 9						
C_X = 0.002 µF, R_X = 100 kΩ		5.0	198	210	230	
		10	200	212	232	
		15	202	214	234	
C_X = 0.1 µF, R_X = 100 kΩ		5.0	9.3	9.86	10.5	ms
		10	9.4	10	10.6	
		15	9.5	10.14	10.7	
C_X = 10 µF, R_X = 100 kΩ		5.0	0.91	0.965	1.03	s
		10	0.92	0.98	1.04	
		15	0.93	0.99	1.06	
Pulse Width Match between circuits in	100	5.0	–	± 1.0	± 5.0	%
the same package.	$[(T_1 - T_2)/T_1]$	10	–	± 1.0	± 5.0	
C_X = 0.1 µF, R_X = 100 kΩ		15	–	± 1.0	± 5.0	

4. The formulas given are for the typical characteristics only at 25°C.
5. Data labelled “Typ” is not to be used for design purposes but is intended as an indication of the IC’s potential performance.

OPERATING CONDITIONS

External Timing Resistance	R_X	–	5.0	–	(Note 6)	kΩ
External Timing Capacitance	C_X	–	0	–	No Limit (Note 7)	µF

6. The maximum usable resistance R_X is a function of the leakage of the capacitor C_X, leakage of the MC14538B, and leakage due to board layout and surface resistance. Susceptibility to externally induced noise signals may occur for R_X > 1 MΩ..
7. If C_X > 15 µF, use discharge protection diode per Fig. 11.

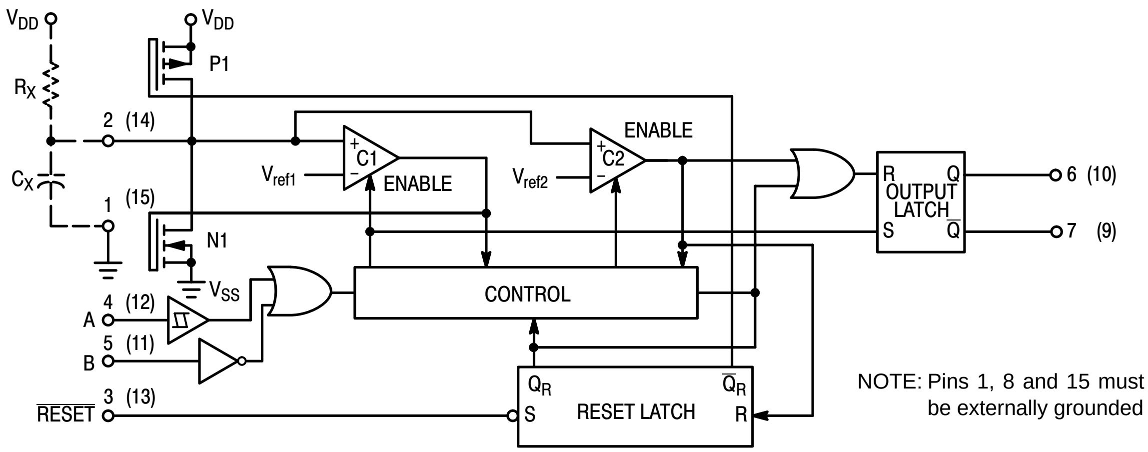


Figure 1. Logic Diagram (1/2 of DevIce Shown)

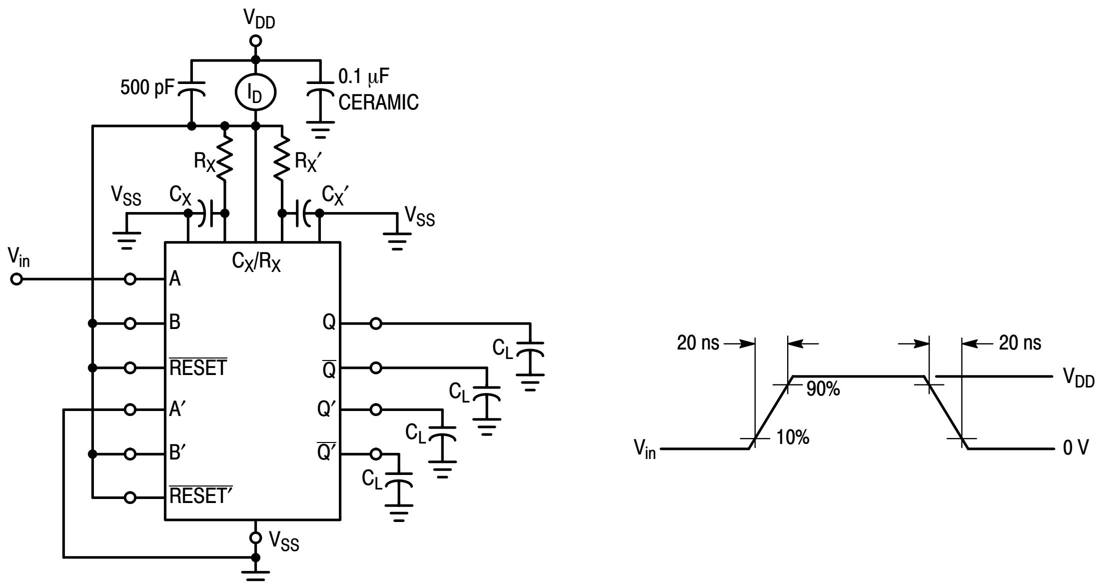
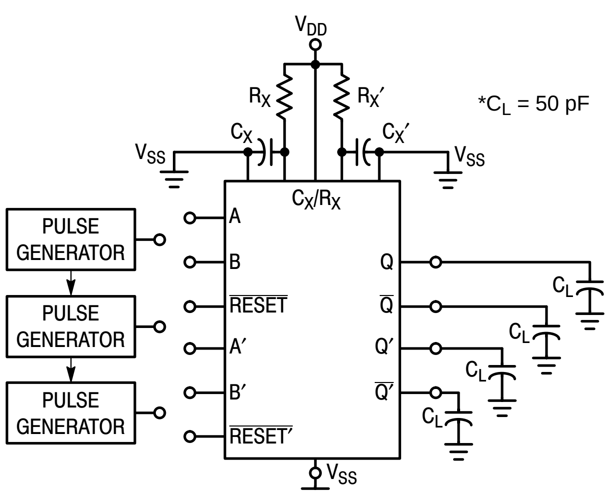


Figure 2. Power Dissipation Test Circuit and Waveforms



INPUT CONNECTIONS

Characteristics	Reset	A	B
t_{PLH}, t_{PHL}, t_{TLH}, t_{THL}, T, t_{WH}, t_{WL}	V_{DD}	PG1	V_{DD}
t_{PLH}, t_{PHL}, t_{TLH}, t_{THL}, T, t_{WH}, t_{WL}	V_{DD}	V_{SS}	PG2
$t_{PLH(R)}$, $t_{PHL(R)}$, t_{WH}, t_{WL}	PG3	PG1	PG2

*Includes capacitance of probes, wiring, and fixture parasitic.

NOTE: Switching test waveforms for PG1, PG2, PG3 are shown In Figure 4.

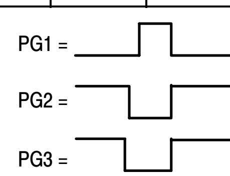


Figure 3. Switching Test Circuit

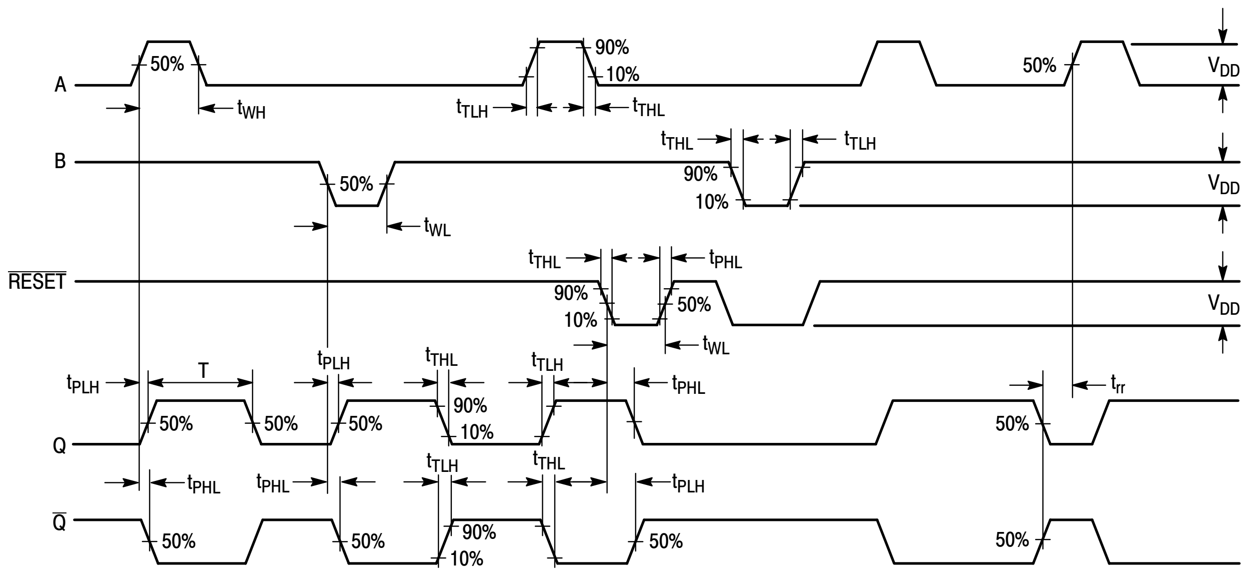


Figure 4. Switching Test Waveforms

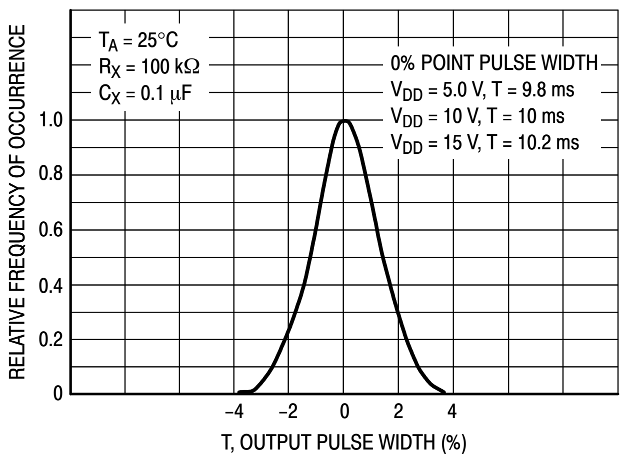


Figure 5. Typical Normalized Distribution of Units for Output Pulse Width

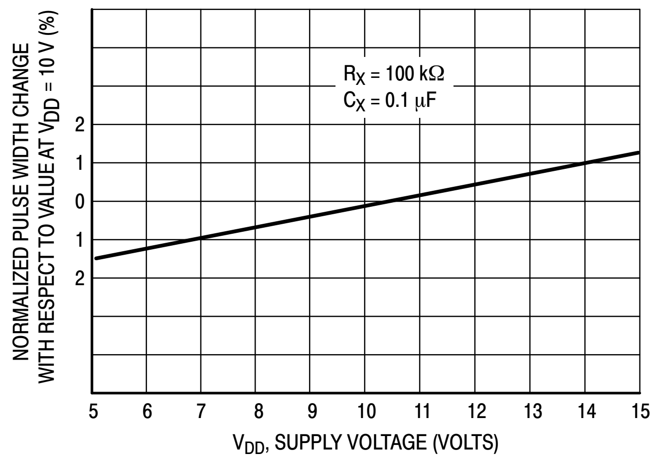


Figure 6. Typical Pulse Width Variation as a Function of Supply Voltage V_{DD}

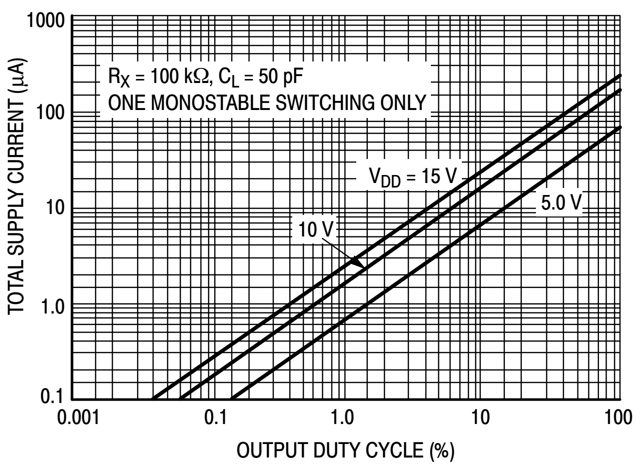


Figure 7. Typical Total Supply Current versus Output Duty Cycle

FUNCTION TABLE

Inputs			Outputs	
Reset	A	B	Q	Q̄
H	↑	H	⊓	⊔
H	L	↓	⊓	⊔
H	↑ ↓	L	Not Triggered	
H	H	↑ ↓	Not Triggered	
H	L, H, ↓	H	Not Triggered	
H	L	L, H, ↑	Not Triggered	
L	X	X	L	H
↓ ↑	X	X	Not Triggered	

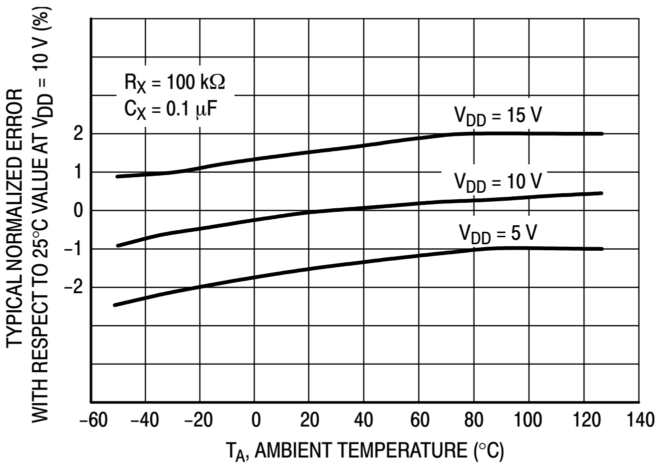


Figure 8. Typical Error of Pulse Width Equation versus Temperature

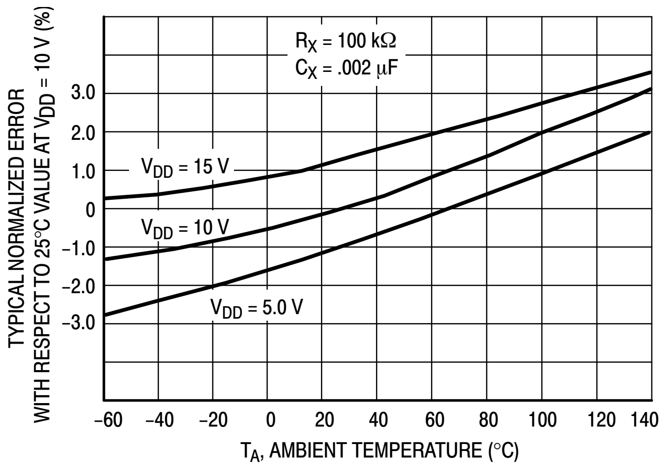


Figure 9. Typical Error of Pulse Width Equation versus Temperature

THEORY OF OPERATION

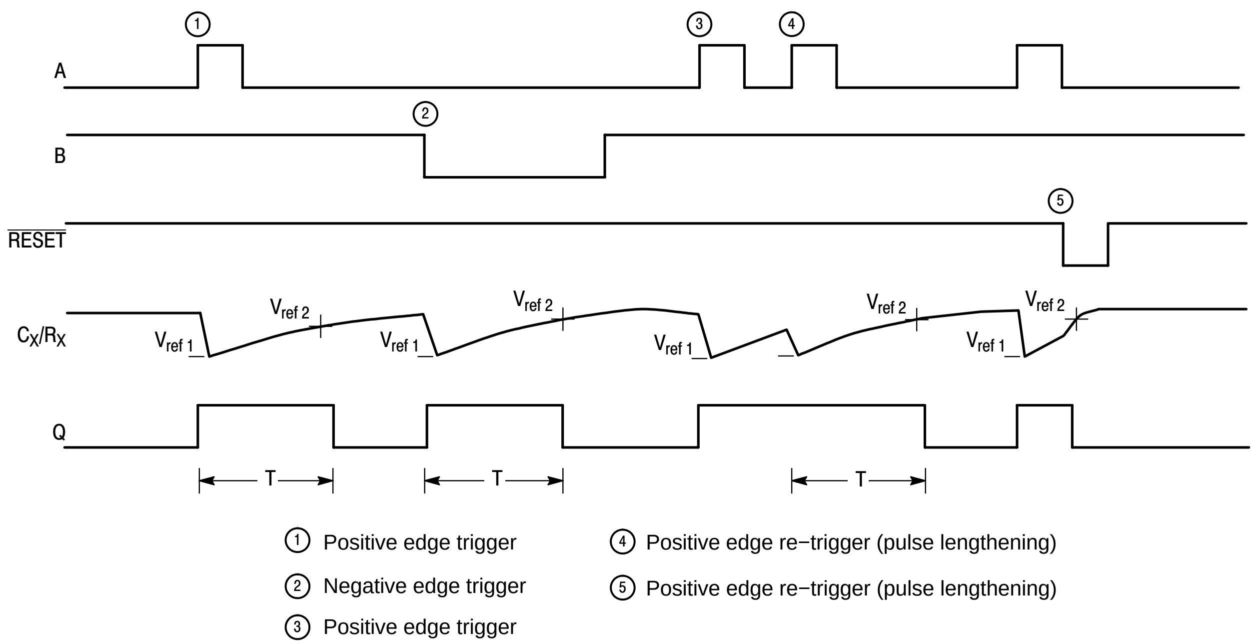


Figure 10. Timing Operation

TRIGGER OPERATION

The block diagram of the MC14538B is shown in Figure 1, with circuit operation following.

As shown in Figure 1 and 10, before an input trigger occurs, the monostable is in the quiescent state with the Q output low, and the timing capacitor C_X completely charged to V_{DD}. When the trigger input A goes from V_{SS} to V_{DD} (while inputs B and $\overline{\text{Reset}}$ are held to V_{DD}) a valid trigger is recognized, which turns on comparator C1 and N−channel transistor N1 ①. At the same time the output latch is set. With transistor N1 on, the capacitor C_X rapidly discharges toward V_{SS} until V_{ref1} is reached. At this point the output of comparator C1 changes state and transistor N1 turns off. Comparator C1 then turns off while at the same time comparator C2 turns on. With transistor N1 off, the capacitor C_X begins to charge through the timing resistor, R_X, toward V_{DD}. When the voltage across C_X equals $V_{ref\,2}$, comparator C2 changes state, causing the output latch to reset (Q goes low) while at the same time disabling comparator C2 ②. This ends at the timing cycle with the monostable in the quiescent state, waiting for the next trigger.

In the quiescent state, C_X is fully charged to V_{DD} causing the current through resistor R_X to be zero. Both comparators are “off” with total device current due only to reverse junction leakages. An added feature of the MC14538B is that the output latch is set via the input trigger without regard to the capacitor voltage. Thus, propagation delay from trigger to Q is independent of the value of C_X, R_X, or the duty cycle of the input waveform.

RETRIGGER OPERATION

The MC14538B is retriggered if a valid trigger occurs ③ followed by another valid trigger ④ before the Q output has returned to the quiescent (zero) state. Any retrigger, after the timing node voltage at pin 2 or 14 has begun to rise from $V_{ref\,1}$, but has not yet reached $V_{ref\,2}$, will cause an increase in output pulse width T. When a valid retrigger is initiated ④, the voltage at C_X/R_X will again drop to $V_{ref\,1}$ before progressing along the RC charging curve toward V_{DD}. The Q output will remain high until time T, after the last valid retrigger.

RESET OPERATION

The MC14538B may be reset during the generation of the output pulse. In the reset mode of operation, an input pulse on $\overline{\text{Reset}}$ sets the reset latch and causes the capacitor to be fast charged to V_{DD} by turning on transistor P1 ⑤. When the voltage on the capacitor reaches $V_{ref\,2}$, the reset latch will clear, and will then be ready to accept another pulse. It the $\overline{\text{Reset}}$ input is held low, any trigger inputs that occur will be inhibited and the Q and $\overline{Q}$ outputs of the output latch will not change. Since the Q output is reset when an input low level is detected on the $\overline{\text{Reset}}$ input, the output pulse T can be made significantly shorter than the minimum pulse width specification.

POWER−DOWN CONSIDERATIONS

Large capacitance values can cause problems due to the large amount of energy stored. When a system containing the MC14538B is powered down, the capacitor voltage may discharge from V_{DD} through the standard protection diodes at pin 2 or 14. Current through the protection diodes should be limited to 10 mA and therefore the discharge time of the V_{DD} supply must not be faster than (V_{DD}). (C)/(10 mA). For example, if V_{DD} = 10 V and C_X = 10 μF, the V_{DD} supply should discharge no faster than (10 V) x (10 μF)/(10 mA) = 10 ms. This is normally not a problem since power supplies are heavily filtered and cannot discharge at this rate.

When a more rapid decrease of V_{DD} to zero volts occurs, the MC14538B can sustain damage. To avoid this possibility use an external clamping diode, D_X, connected as shown in Fig. 11.

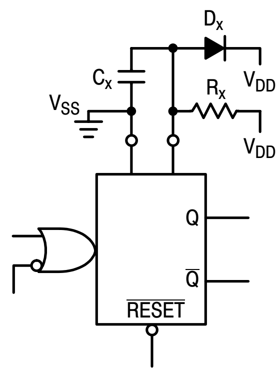


Figure 11. Use of a Diode to Limit Power Down Current Surge

TYPICAL APPLICATIONS

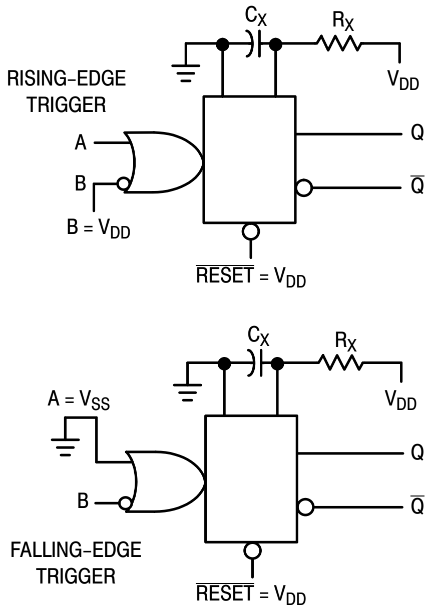


Figure 12. Retriggerable Monostables Circuitry

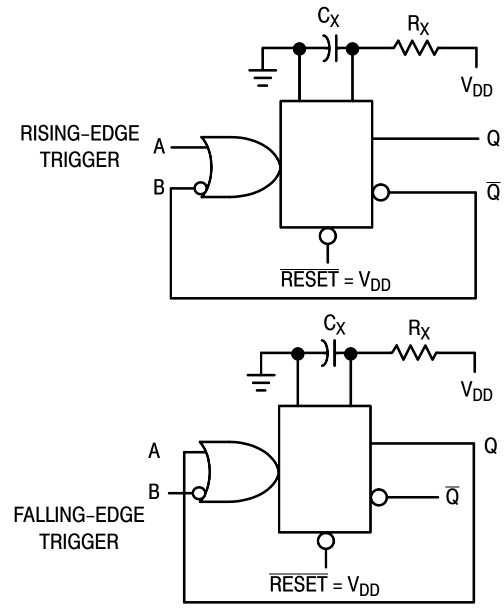


Figure 13. Non−Retriggerable Monostables Circuitry

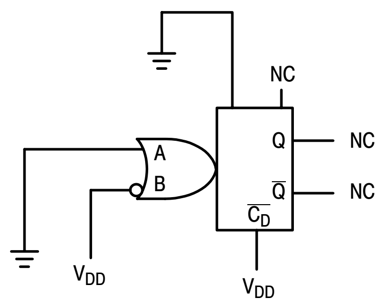
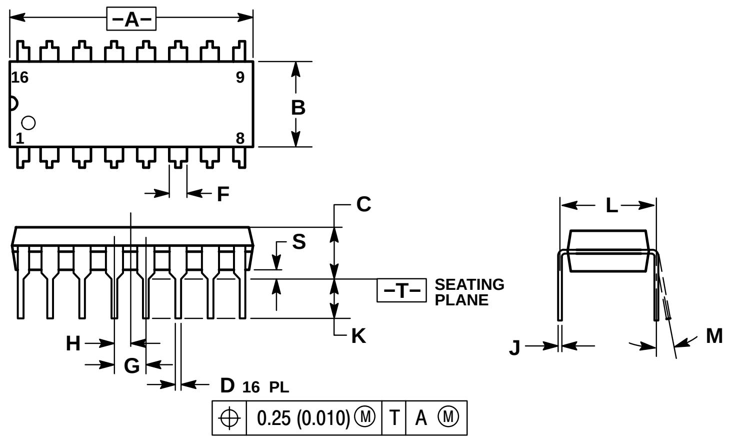


Figure 14. Connection of Unused Sections

PACKAGE DIMENSIONS

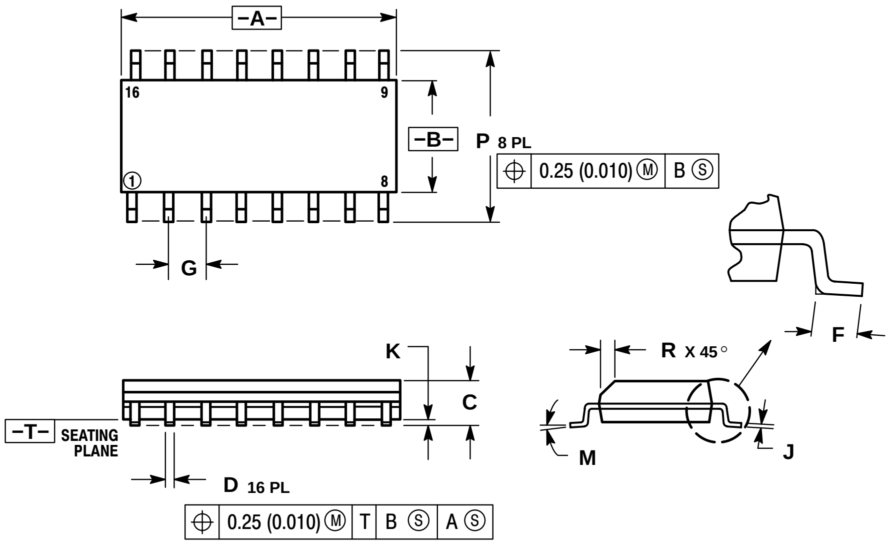
PDIP−16
P SUFFIX
PLASTIC DIP PACKAGE
CASE 648−08
ISSUE T



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0 °	10 °	0 °	10 °
S	0.020	0.040	0.51	1.01

SOIC−16
D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751B−05
ISSUE J

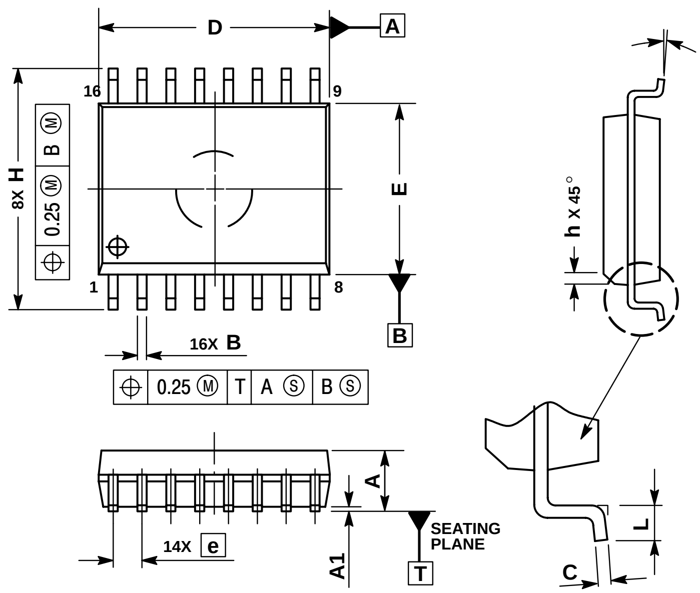


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7 °	0 °	7 °
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

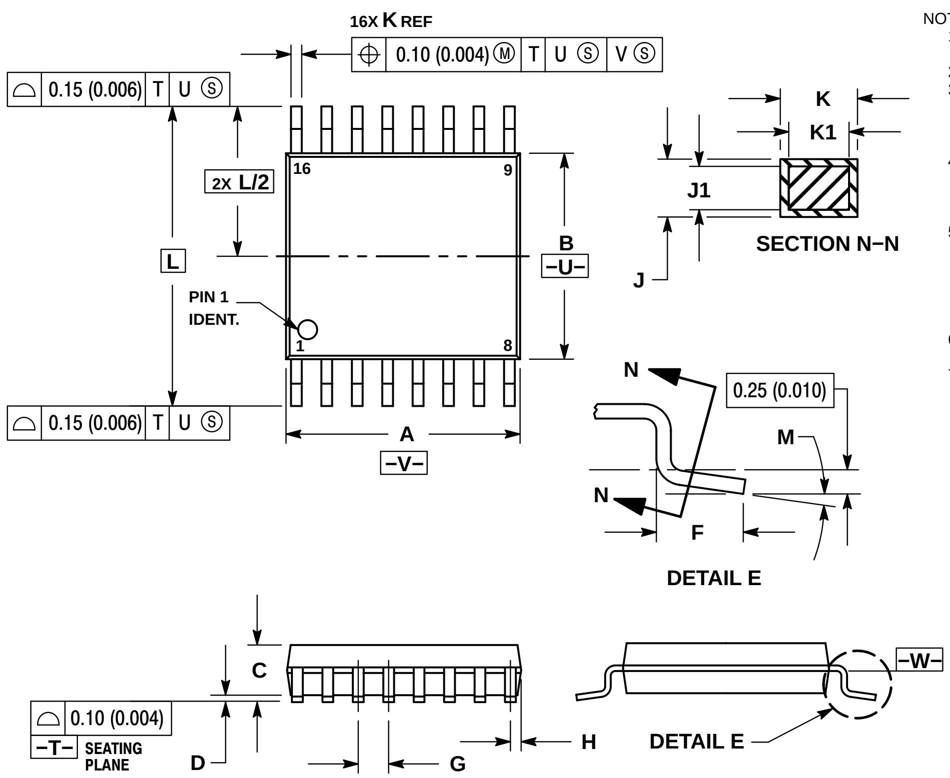
SOIC−16 WB
DW SUFFIX
PLASTIC SOIC PACKAGE
CASE 751G−03
ISSUE C



NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INLCUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF THE B DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS	
DIM	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	10.15	10.45
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
q	0 °	7 °

TSSOP−16
DT SUFFIX
PLASTIC TSSOP PACKAGE
CASE 948F−01
ISSUE A

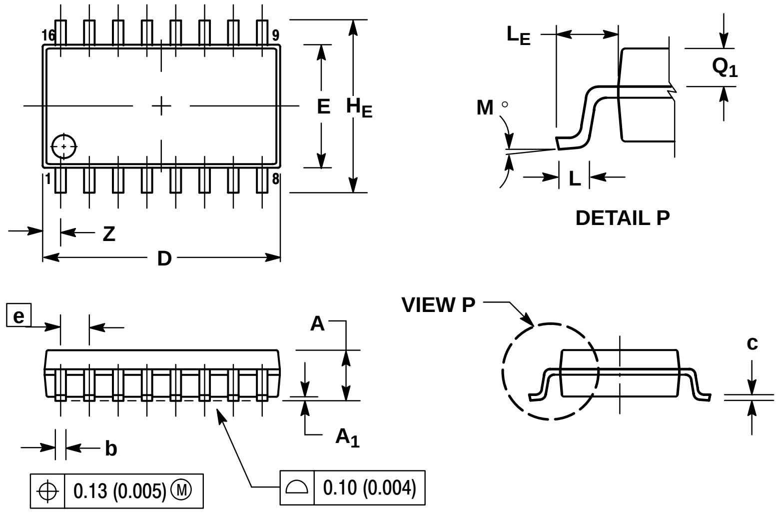


NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	−−−	1.20	−−−	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °

PACKAGE DIMENSIONS

SOEIAJ−16
F SUFFIX
PLASTIC EIAJ SOIC PACKAGE
CASE 966−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A_1	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H_E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L_E	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10 °
Q_1	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

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